Title (en)
METHOD FOR PRODUCING A PLATED-THROUGH HOLE IN A MULTILAYER PRINTED CIRCUIT BOARD

Title (de)
VERFAHREN ZUR HERSTELLUNG EINER DURCHKONTAKTIERUNG BEI EINER MEHRLAGEN-LEITERPLATTE

Title (fr)
PROCÉDÉ DE FABRICATION D'UN CONTACT TRAVERSANT DANS UNE CARTE DE CIRCUIT IMPRIMÉ MULTICOUCHE

Publication
EP 3257335 A1 20171220 (DE)

Application
EP 16706131 A 20160206

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Abstract (en)
[origin: WO2016128127A1] Method for producing a plated-through hole between conductor tracks which are arranged at the top and at the bottom in a multilayer printed circuit board which is composed of a printed circuit board material and comprises at least one copper profile which is embedded in the composite of the multilayer printed circuit board, wherein the plated-through hole is produced by the following method steps: producing a first bore with a first bore diameter through the multilayer printed circuit board by drilling through the top and the bottom conductor track and the embedded copper profile; filling the first bore with an insulating filling material; producing a second bore coaxially in relation to the first bore with a second, smaller bore diameter than the bore diameter of the first bore; lining the bore wall of the second bore with an electrically conductive material and in this way making electrical contact with the top and bottom conductor tracks.

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